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Ichikawa et al.

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(54) **LIGHT EMITTING DEVICE, RESIN PACKAGE, RESIN-MOLDED BODY, AND METHODS FOR MANUFACTURING LIGHT EMITTING DEVICE, RESIN PACKAGE AND RESIN-MOLDED BODY**

(58) **Field of Classification Search**
CPC H01L 33/0033; H01L 33/385; H01L 2924/181; H01L 2224/48247; H01L 33/486; H01L 33/60; H01L 33/641; H01L 2924/00; B29C 45/055; B29C 45/4655; B29C 45/14655
USPC 438/26; 361/820; 257/100, 99
See application file for complete search history.

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Related U.S. Application Data

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(30) **Foreign Application Priority Data**

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(57) **ABSTRACT**

A method of manufacturing a light emitting device having a resin package which provides an optical reflectivity equal to or more than 70% at a wavelength between 350 nm and 800 nm after thermal curing, and in which a resin part and a lead are formed in a substantially same plane in an outer side surface, includes a step of sandwiching a lead frame provided with a notch part, by means of an upper mold and a lower mold, a step of transfer-molding a thermosetting resin containing a light reflecting material in a mold sandwiched by the upper mold and the lower mold to form a resin-molded body in the lead frame and a step of cutting the resin-molded body and the lead frame along the notch part.

(51) **Int. Cl.**

H01L 21/00 (2006.01)
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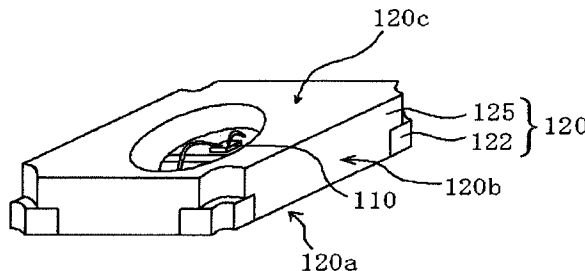
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Fig. 1

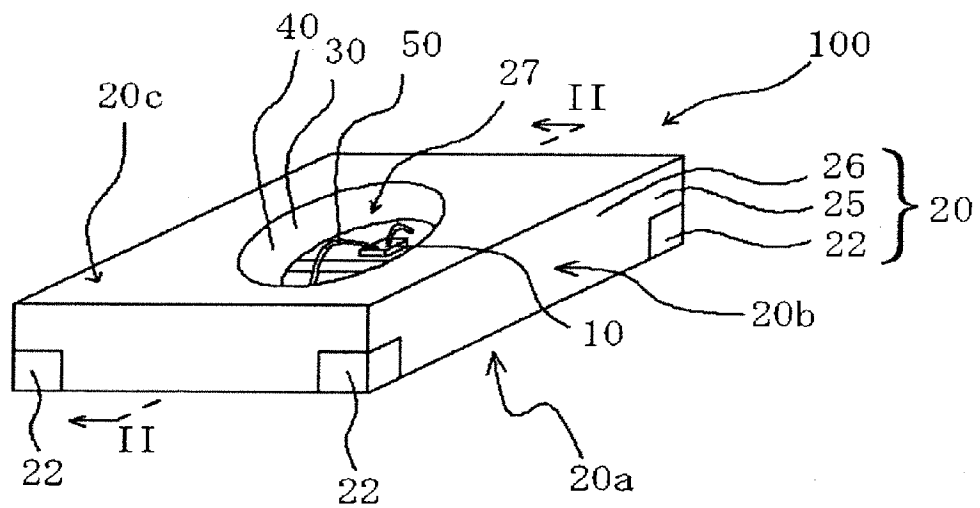
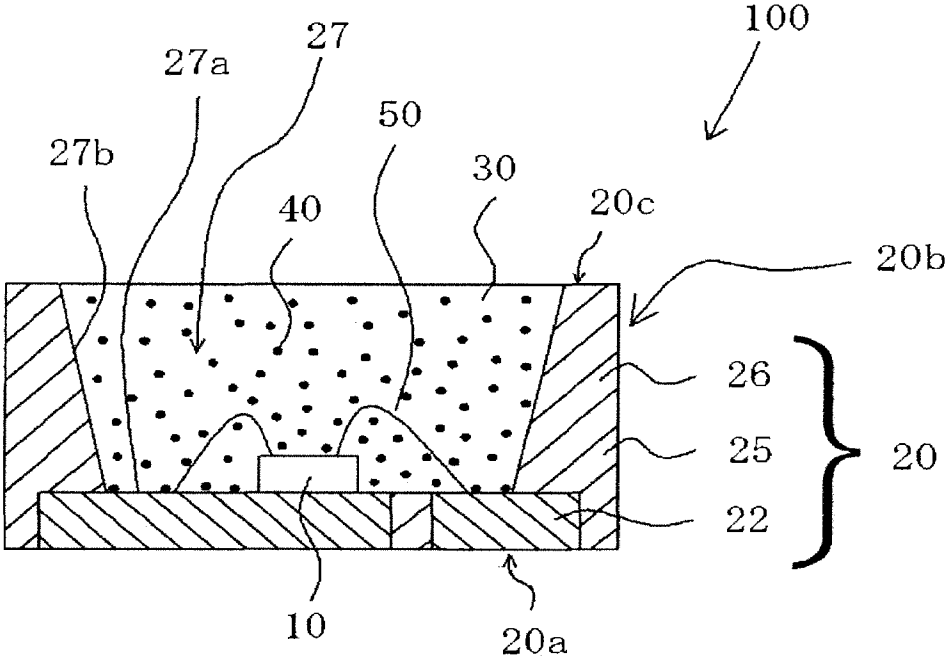


Fig. 2



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